XILINX®

PK145 (v1.3) October 5, 2011

100% Material Declaration Data Sheet BG560

Average Weight: 10.9443 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.321700**	**2.939%**
	Silicon	7440-21-3	100.00		0.321700	
Die Attach Material					**0.002500**	**0.023%**
	Silver	7440-22-4	75.00		0.001875	
	Resin	Trade Secret	25.00		0.000625	
Mold Compound					**0.646000**	**5.903%**
	Resin	Trade Secret	26.00		0.167960	
	Silica	60676-86-0	74.00	Filler	0.478040	
Gold Wire					**0.024000**	**0.219%**
	Gold	7440-57-5	100.00		0.024000	
Dam					**0.014600**	**0.133%**
	Damming Material	Trade Secret	100.00		0.014600	
Solder Balls					**1.752000**	**16.008%**
	Tin (Sn)	7440-31-5	63.00		1.103760	
	Lead (Pb)	7439-92-1	37.00		0.648240	
Laminate					**0.790000**	**7.218%**
	BT (core)	Trade Secret	60.89		0.481000	
	Solder mask (EP)	Trade Secret	21.27		0.168000	
	Copper (Cu)	7440-50-8	15.44		0.122000	
	Nickel (Ni)	7440-02-0	1.77		0.014000	
	Gold (Au)	7440-57-5	0.63		0.005000	
Heat Spreader					**7.064500**	**64.550%**
	Copper (Cu)	7440-50-8	97.50		6.887888	
	Iron (Fe)	7439-89-6	2.35	Metal Layer	0.166016	
	Phosphorus (P)	7723-14-0	0.03	Metal Layer	0.002119	
	Zinc (Zn)	7440-66-6	0.12	Metal Layer	0.008477	
Heat Spreader Adhesive					**0.329000**	**3.006%**
	Nickel (Ni)	7440-02-0	100.00		0.329000	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/06/06	1.0	Initial Xilinx release.
07/12/06	1.1	100% Material Declaration
09/28/06	1.2	Update component directory
01/08/07	1.2.1	Corrected Gold Wire CAS# entry
10/05/11	1.3	Update component weights and descriptions

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